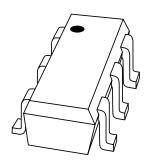
## DISCRETE SEMICONDUCTORS

## DATA SHEET



# **BGA2748**MMIC wideband amplifier

Product specification Supersedes data of 2002 Jul 03 2010 Sep 13



## **MMIC** wideband amplifier

**BGA2748** 

#### **FEATURES**

- · Internally matched
- Wide frequency range
- Optimized for 900 MHz
- · Excellent isolation
- Low noise
- Unconditionally stable.

## **APPLICATIONS**

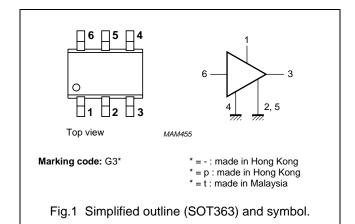
- · Cable systems
- · LNB IF amplifiers
- · General purpose
- ISM.

#### **DESCRIPTION**

Silicon Monolitic Microwave Integrated Circuit (MMIC) wideband amplifier with internal matching circuit in a 6-pin SOT363 SMD plastic package.

#### **PINNING**

PIN	DESCRIPTION
1	V <sub>S</sub>
2, 5	GND2
3	RF out
4	GND1
6	RF in



## **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
Vs	DC supply voltage		3	4	V
I <sub>S</sub>	DC supply current		5.7	_	mA
s <sub>21</sub>   <sup>2</sup>	insertion power gain	f = 1 GHz	21.8	_	dB
NF	noise figure	f = 1 GHz	1.9	_	dB
P <sub>L(sat)</sub>	saturated load power	f = 1 GHz	-2.3	_	dBm

## **CAUTION**

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling.

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## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Vs	DC supply voltage	RF input AC coupled	_	4	V
I <sub>S</sub>	supply current		_	15	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 80 °C	_	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	operating junction temperature		_	150	°C
P <sub>D</sub>	maximum drive power		_	10	dBm

## THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to solder point	$P_{tot} = 200 \text{ mW}; T_s \le 80 ^{\circ}\text{C}$	300	K/W

## **CHARACTERISTICS**

 $V_S$  = 3 V;  $I_S$  = 5.7 mA; f = 1 GHz;  $T_j$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Is	supply current		4.5	5.7	8	mA
s <sub>21</sub>   <sup>2</sup>	insertion power gain	f = 1 GHz	_	21.8	_	dB
		f = 2 GHz	_	18.5	_	dB
R <sub>L IN</sub>	return losses input	f = 1 GHz	_	18	_	dB
		f = 2 GHz	_	14	_	dB
R <sub>L OUT</sub>	return losses output	f = 1 GHz	_	7	_	dB
		f = 2 GHz	-	8	_	dB
NF	noise figure	f = 1 GHz	_	1.9	_	dB
		f = 2 GHz	_	2.4	_	dB
BW	bandwidth	at $ s_{21} ^2$ –3 dB below flat gain at 1 GHz	_	1.9	_	GHz
P <sub>L(sat)</sub>	saturated load power	f = 1 GHz	_	-2.3	_	dBm
		f = 2 GHz	_	-3.3	_	dBm
P <sub>L 1 dB</sub>	load power	at 1 dB gain compression; f = 1 GHz	_	-9.2	_	dBm
		at 1 dB gain compression; f = 2 GHz	_	-10.9	_	dBm
IP3 <sub>(in)</sub>	input intercept point	f = 1 GHz	_	-23.7	_	dBm
		f = 2 GHz	_	-19.9	_	dBm
IP3 <sub>(out)</sub>	output intercept point	f = 1 GHz	_	-1.9	_	dBm
		f = 2 GHz	_	-1.4	_	dBm

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#### APPLICATION INFORMATION

Figure 2 shows a typical application circuit for the BGA2748 MMIC. The device is internally matched to 50  $\Omega$ , and therefore does not need any external matching. The value of the input and output DC blocking capacitors C2, C3 should be not more than 100 pF for applications above 100 MHz. However, when the device is operated below 100 MHz, the capacitor value should be increased.

The 22 nF supply decoupling capacitor, C1 should be located as closely as possible to the MMIC.

Separate paths must be used for the ground planes of the ground pins GND1, GND2, and these paths must be as short as possible. When using vias, use multiple vias per pin in order to limit ground path inductance.

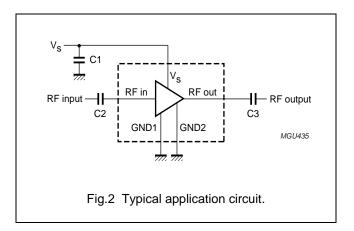
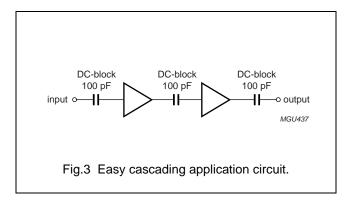


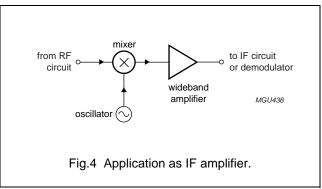
Figure 3 shows two cascaded MMICs. This configuration doubles overall gain while preserving broadband characteristics. Supply decoupling and grounding conditions for each MMIC are the same as those for the circuit of Fig.2.

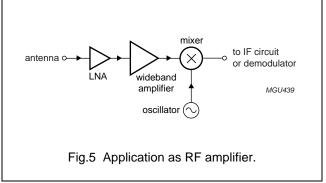
The excellent wideband characteristics of the MMIC make it and ideal building block in IF amplifier applications such as LBNs (see Fig.4).

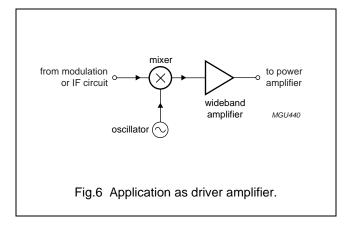
As a buffer amplifier between an LNA and a mixer in a receiver circuit, the MMIC offers an easy matching, low noise solution (see Fig.5).

In Fig.6 the MMIC is used as a driver to the power amplifier in part of a transmitter circuit. Good linear performance and matched input and output offer quick design solutions in such applications.







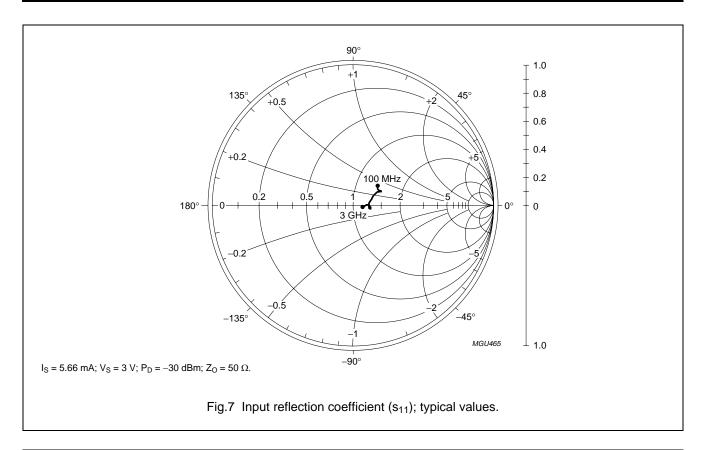


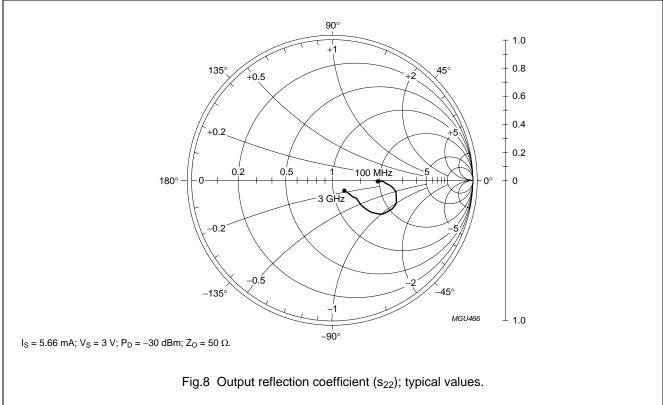
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## MMIC wideband amplifier

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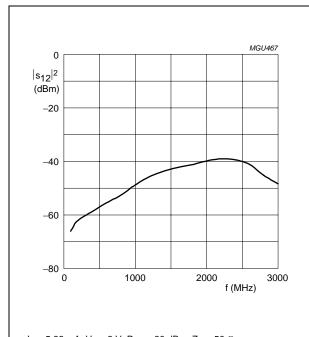


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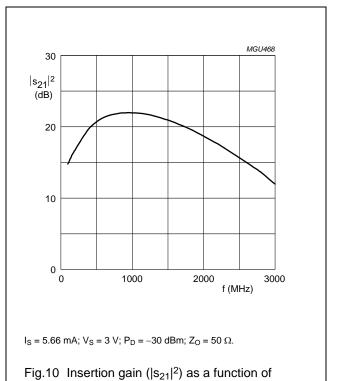
## MMIC wideband amplifier

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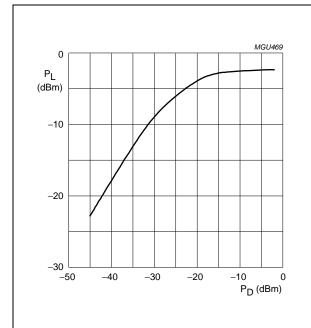


 $I_S$  = 5.66 mA;  $V_S$  = 3 V;  $P_D$  = –30 dBm;  $Z_O$  = 50  $\Omega.$ 

Fig.9 Isolation ( $|s_{12}|^2$ ) as a function of frequency; typical values.

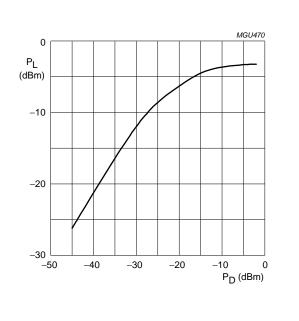


frequency; typical values.



 $V_S=3~V;\,f=1~GHz;\,Z_O=50~\Omega.$ 

Fig.11 Load power as a function of drive power at 1 GHz; typical values.

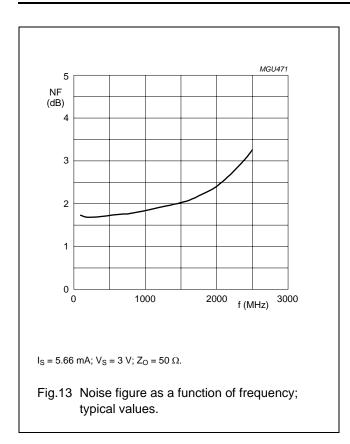


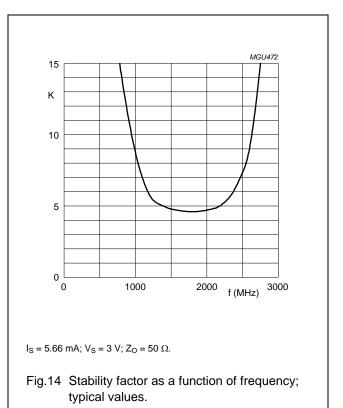
 $V_S$  = 3 V; f = 2 GHz;  $Z_O$  = 50  $\Omega$ .

Fig.12 Load power as a function of drive power at 2 GHz; typical values.

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**Table 1** Scattering parameters:  $I_S = 5.66$  mA;  $V_S = 3$  V;  $P_D = -30$  dBm;  $Z_O = 50$   $\Omega$ ;  $T_{amb} = 25$  °C

•	S <sub>11</sub>		s <sub>21</sub>		s <sub>12</sub>		s <sub>22</sub>		
(MHz)	MAGNITUDE (ratio)	ANGLE (deg)							
100	0.08233	-6.058	5.4700	14.75	0.00049	-92.64	0.32715	-3.589	
200	0.08934	1.505	6.8702	17.10	0.00078	-91.63	0.32763	-2.304	
400	0.10677	1.621	9.7365	5.277	0.00164	-108.6	0.33688	-1.542	
600	0.12257	-2.565	11.586	-12.73	0.00168	-119.4	0.36332	-1.800	
800	0.12902	-8.769	12.372	-31.11	0.00233	-113.0	0.39884	-3.931	
1000	0.12635	-11.24	12.519	-48.70	0.00363	-129.6	0.44177	-8.067	
1200	0.11634	-9.574	12.232	-65.32	0.00551	-140.5	0.47449	-14.54	
1400	0.11643	1.8040	11.550	-81.52	0.00659	-151.4	0.48300	-21.47	
1600	0.12552	14.913	10.664	-96.69	0.00779	-163.4	0.46932	-28.10	
1800	0.15177	23.659	9.6775	-111.1	0.00871	-176.5	0.43106	-34.03	
2000	0.18258	27.689	8.5565	-124.5	0.01025	172.8	0.37882	-38.74	
2200	0.20634	29.316	7.5480	-136.9	0.01124	160.7	0.31996	-41.11	
2400	0.22422	28.365	6.5362	-148.4	0.01078	146.8	0.26441	-40.43	
2600	0.22777	26.661	5.6120	-158.5	0.00884	131.1	0.22542	-37.88	
2800	0.21931	28.691	4.8007	-167.7	0.00548	123.8	0.18502	-38.37	
3000	0.22247	37.201	3.9567	-175.6	0.00384	160.7	0.12693	-37.56	

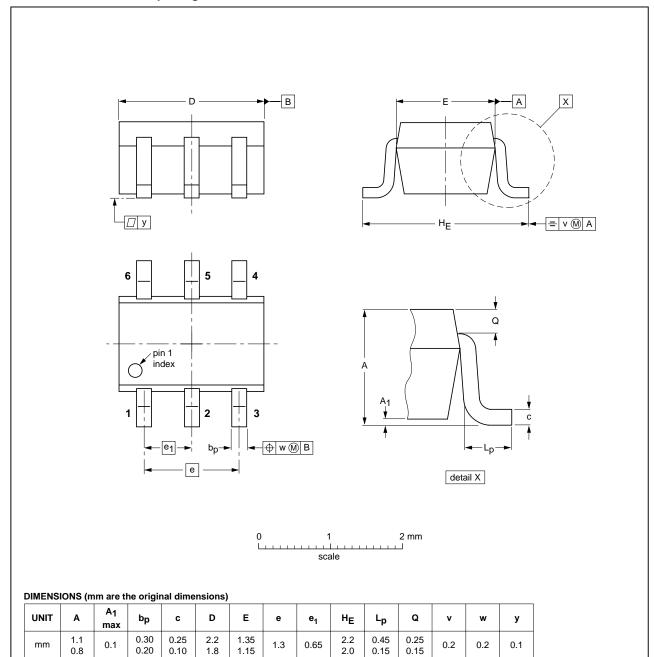
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## **PACKAGE OUTLINE**

## Plastic surface-mounted package; 6 leads

**SOT363** 



OUTLINE		REFERENCES EUROPEAN ISSUE D.			ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	1330E DATE
SOT363			SC-88			<del>04-11-08</del> 06-03-16

## MMIC wideband amplifier

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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